R163-S30 (rev. AAB1) | (rev.AAB2)

Rack Server - 4th/5th Gen Intel® Xeon® Scalable - 1U UP 4-Bay Gen4 NVMe/SATA/SAS | Application: Networ

Hybrid/Private Cloud Server

5th Gen Intel[®] Xeon[®] Scalable Processors

4th Gen Intel® Xeon® Scalable Processors

Intel® Xeon® CPU Max Series

Single processor, LGA 4677

8-Channel RDIMM DDR5 per processor, 16 x DIMMs

Dual ROM Architecture

- 1 x 1Gb/s LAN port (Intel® I210-AT)
- 1 x Dedicated management port
- 4 x 3.5/2.5" Gen4 NVMe/SATA/SAS hot-swappable bays
- 1 x M.2 slot with PCle Gen3 x4 interface
- 2 x FHHL PCIe Gen5 x16 slots
- 2 x OCP 3.0 Gen5 x16 slots
- 1+1 800W 80 PLUS Platinum redundant power supplies



Compare





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OVERVIEW SPECIFICATIONS SUPPORT RESOURCES

R163-S30 (rev. AAB1)

Dimensions (WxHxD, mm)

1U 438 x 43.5 x 710

Motherboard

MS33-DC0

CPU

5th Generation Intel® Xeon® Scalable Processors 4th Generation Intel® Xeon® Scalable Processors Intel® Xeon® CPU Max Series Single processor, CPU TDP up to 350W

Socket

1 x LGA 4677 Socket E

BUY

Chipset

Intel® C741 Chipset

Memory

16 x DIMM slots DDR5 memory supported only 8-Channel memory architecture RDIMM modules up to 96GB supported 3DS RDIMM modules up to 256GB supported

5th Gen Intel® Xeon®: Up to *5600MHz (1DPC), 4400MHz (2DPC) 4th Gen Intel® Xeon®: Up to 4800MHz (1DPC), 4400MHz (2DPC) Intel® Xeon® Max Series: Up to 4800MHz (1DPC), 4400MHz (2DPC)

*5600MHz support under 2DPC configuration requires verified memory and BIOS setup. Please refer to the QVL for more information.

LAN

Rear side:

1 x 1Gb/s LAN port (1 x Intel® I210-AT) Supports NCSI function

1 x 10/100/1000 management LAN

Video

Integrated in Aspeed® AST2600 2D Video Graphic Adapter with PCIe bus interface 1920x1200@60Hz 32bpp, DDR4 SDRAM

Storage

Front side:

4 x 3.5"/2.5" Gen4 NVMe/SATA/SAS hot-swappable bays

SAS card is required for SAS devices support

SAS

Depends on SAS add-on card

RAID

Intel® SATA RAID 0/1/10/5

Expansion Slots

Riser Card CRS1010:

- 1 x PCle x16 (Gen5 x16) FHHL slot

Riser Card CRS101P:

- 1 x PCIe x16 (Gen5 x16) FHHL slot

2 x OCP 3.0 slots with PCle Gen5 x16 bandwidth Support NCSI function

- 1 x M.2 slot:
- M-key
- PCIe Gen3 x4, from PCH
- Supports 2280/22110 cards

Internal I/O

1 x TPM header

1 x VROC connector

Front I/O

- 2 x USB 3.2 Gen1
- 1 x Power button with LED
- 1 x ID button with LED
- 1 x NMI button
- 1 x Reset button
- 1 x LAN activity LED
- 1 x HDD activity LED
- 1 x System status LED

Rear I/O

2 x USB 3.2 Gen1

- 1 x Mini-DP
- 1 x RJ45
- 1 x MLAN
- 1 x ID button with LED

Backplane Board

Speed and bandwidth:

PCIe Gen4 x4 or SATA 6Gb/s or SAS 12Gb/s

TPM

1 x TPM header with SPI interface Optional TPM2.0 kit: CTM010

Power Supply

1+1 800W 80 PLUS Platinum redundant power supplies

AC Input:

- 100-240V~/ 10-4A, 50-60Hz

DC Input:

- 240Vdc/ 4.5A

DC Output:

- Max 800W
- + 12V/66A
- + 12Vsb/ 2.5A

Note: The default power supply is based on a basic system configuration. Please contact with technical representatives to determine the best power supply selection for your system configuration requirements and preferred efficiency.

System Management

Aspeed® AST2600 management controller GIGABYTE Management Console (AMI MegaRAC SP-X) web interface

Dashboard

HTML5 KVM

Sensor Monitor (Voltage, RPM, Temperature, CPU Status ...etc.)

Sensor Reading History Data

FRU Information

SEL Log in Linear Storage / Circular Storage Policy

Hardware Inventory

Fan Profile

System Firewall

Power Consumption

Power Control

Advanced power capping

LDAP / AD / RADIUS Support Backup & Restore Configuration

Remote BIOS/BMC/CPLD Update

Event Log Filter

User Management

Media Redirection Settings

PAM Order Settings

SSL Settings

SMTP Settings

OS Compatibility

Please refer to OS compatibility table in support page

Additional certifications:

Windows Server 2022 (x64)

System Fans

4 x 40x40x56mm (29.700rpm)

2 x 40x40x28mm (25,000rpm)

Operating Properties

Operating temperature: 10°C to 35°C

Operating humidity: 8%-80% (non-condensing)

Non-operating temperature: -40°C to 60°C

Non-operating humidity: 20%-95% (non-condensing)

Packaging Dimensions

977 x 588 x 236 mm

Packaging Content

- 1 x R163-S30
- 1 x CPU heatsink
- 1 x Mini-DP to D-Sub cable
- 3 x Carrier clips
- 1 x 2-Section Rail kit

Part Numbers

- Barebone package (4th/5th Gen): 6NR163S30DR000ABB1*
- Barebone package (4th Gen): 6NR163S30DR000AAB1*
- Motherboard: 9MS33DC0UR-000
- 2-Section Rail kit (CMA not supported): 25HB2-3A0203-K0R
- CPU heatsink: 25ST1-4Z3200-S7R
- M.2 heatsink: 12SP2-11000E-00R
- Front panel board CFP1010: 9CFP1010NR-00
- Backplane board CBP1047: 9CBP1047NR-00
- Fan module: 25ST2-405623-A0R/25ST2-442828-D0R
- Riser card CRS101O: 9CRS101ONR-00
- Riser card CRS101P: 9CRS101PNR-00
- Mini-DP to D-Sub cable: 25CRN-200801-K1R
- Power supply: 25EP0-208004-L0S

Optional parts:

- 3-Section Rail kit (Supports CMA): 25HB2-A56120-K0R
- Cable Management Arm: 25HBZ-R18100-K0R